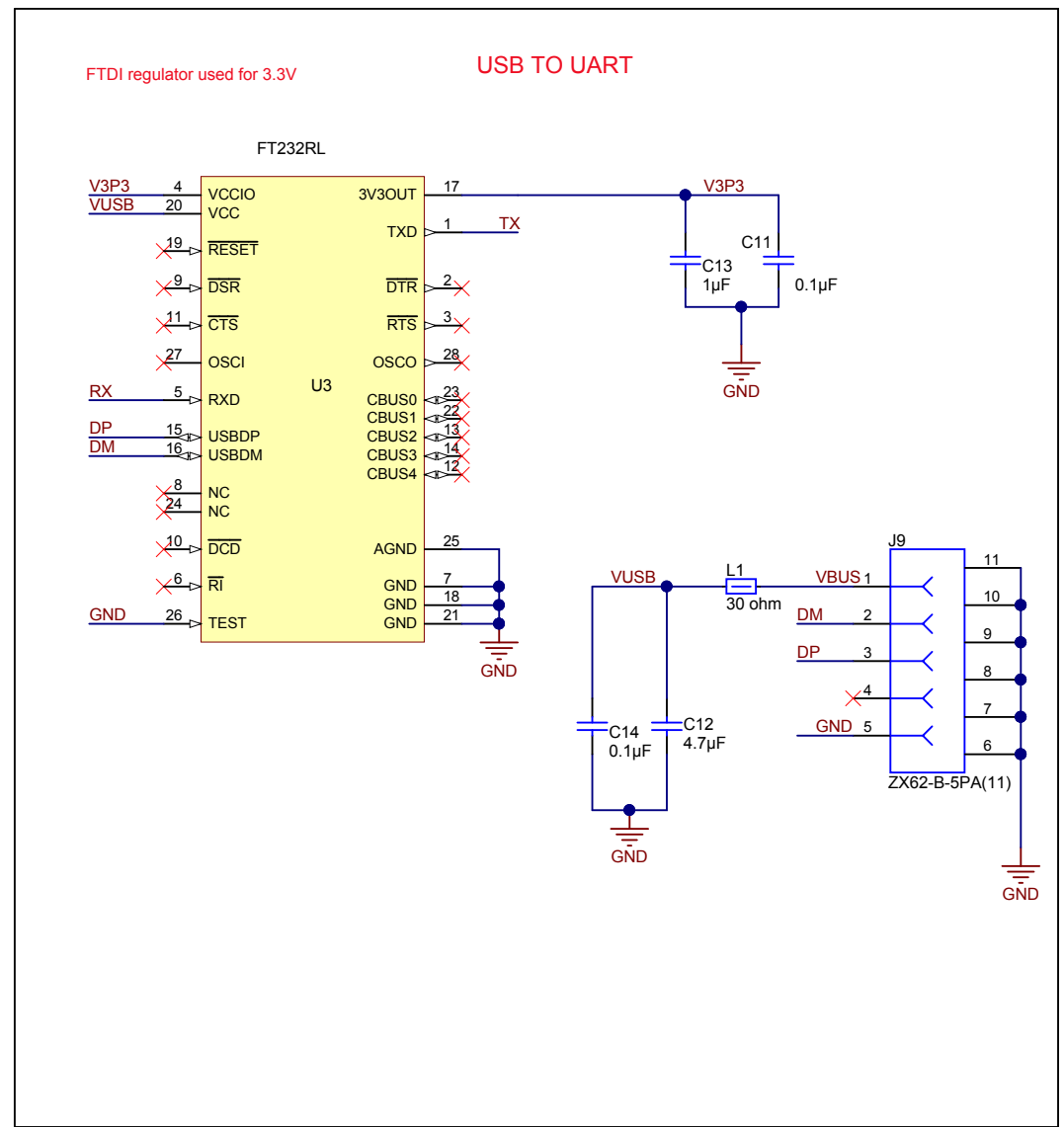
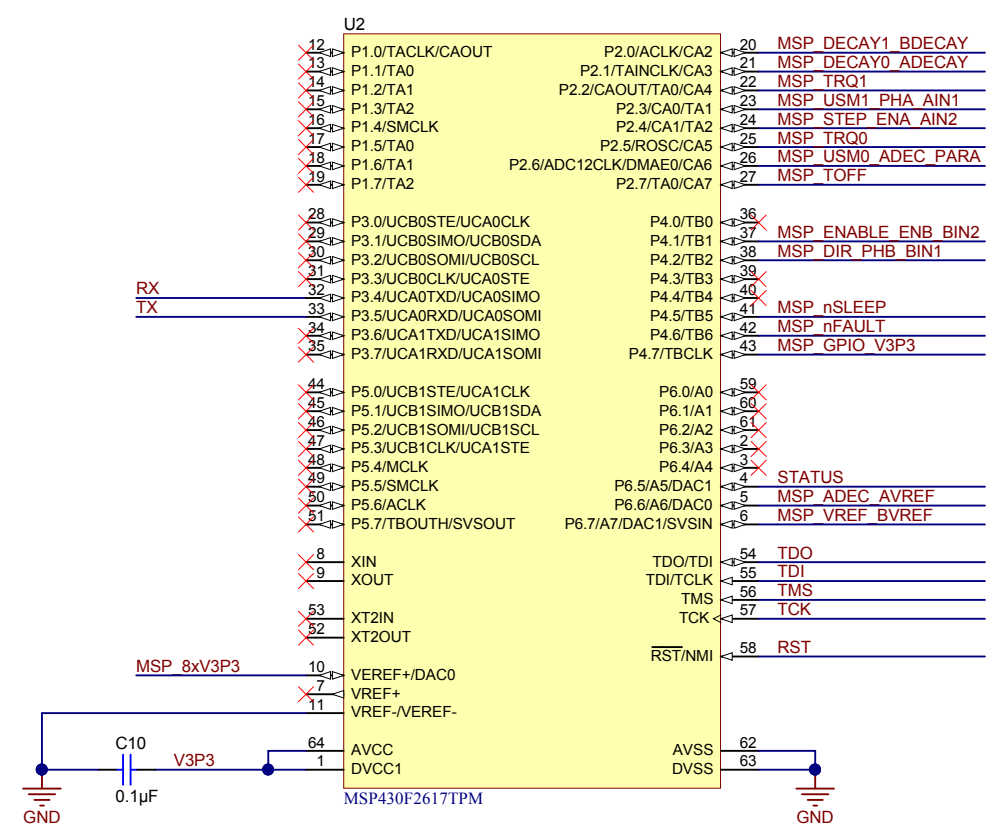
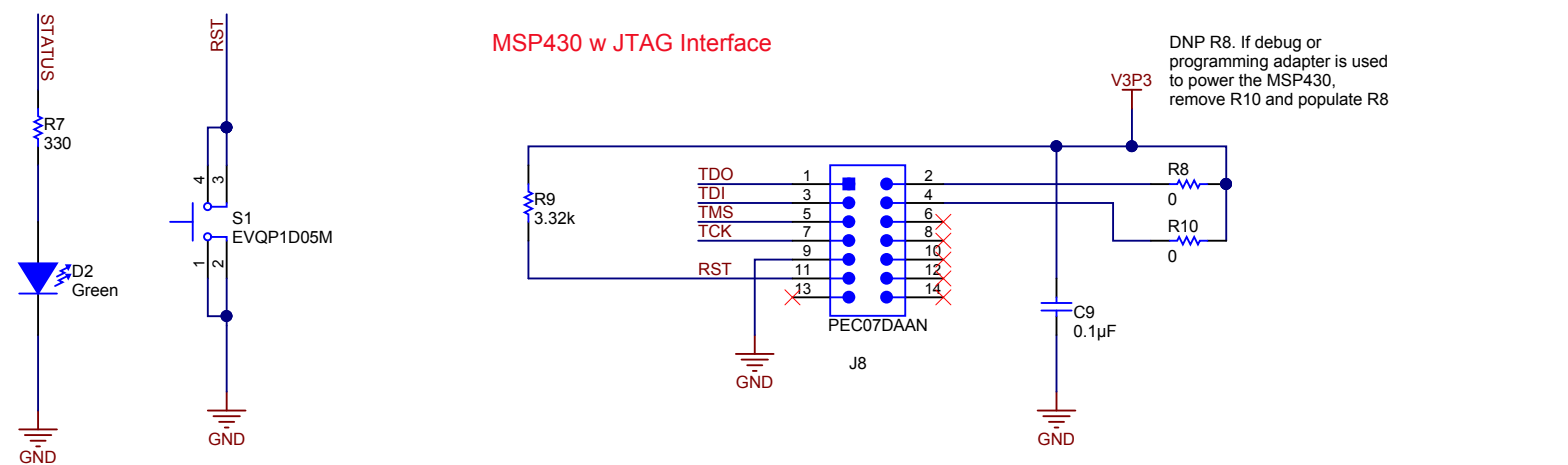


Orderable: DRV8880EVM	Designed for: Public Release	Mod. Date: 11/9/2015
TID #: TIDA-00830	Project Title: DRV888xEVM	
Number: 00830	Rev: A	Sheet Title: DRV888xEVM Motor Driver Connections
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 3
Drawn By:	File: TIDA-00830_DRV888x.SchDoc	Size: B
Engineer: Rick Duncan	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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Orderable: DRV8880EVM	Designed for: Public Release	Mod. Date: 11/9/2015
TID #: TIDA-00830	Project Title: DRV888xEVM	
Number: 00830	Rev: A	Sheet Title: DRV888xEVM Microcontroller Connections
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: Rick Duncan	File: TIDA-00830_MSP430F2617.SchDoc	Size: B
Engineer: Rick Duncan	Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>	

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DNP  
FID1

DNP  
FID2

DNP  
FID3

PCB Number: 00830  
PCB Rev: A

PCB  
LOGO  
Texas Instruments



PCB  
LOGO  
Pb-Free Symbol

PCB  
LOGO  
FCC disclaimer

LBL1  
PCB Label  
Size: 0.65" x 0.20"

Label Table	
Variant	Label Text
001	DRV8880EVM
002	DRV8881EEVM
003	DRV8881PEVM

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

ZZ5  
Assembly Note  
Shorting plug TP7 shall be raised to minimum height of 250mils above PCB

Orderable: DRV8880EVM	Designed for: Public Release	Mod. Date: 11/9/2015	<p>TEXAS INSTRUMENTS</p> <p>http://www.ti.com</p> <p>© Texas Instruments 2015</p>
TID #: TIDA-00830	Project Title: DRV888xEVM		
Number: 00830	Rev: A	Sheet Title: DRV888xEVM Hardware and Notes	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By: Rick Duncan	File: TIDA-00830_Hardware.SchDoc	Size: B	
Engineer: Rick Duncan	Contact: http://www.ti.com/support		

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